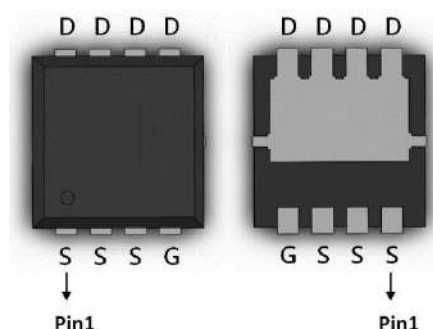


P-Channel Enhancement Mode Power MOSFET

Features:

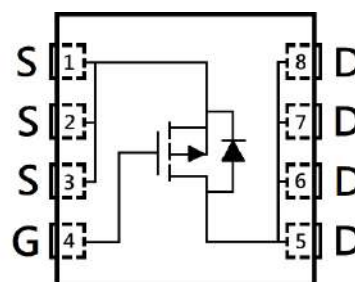
- Single Drive Requirement
- Low On Resistance
- Fast Switching Characteristic

DFN3×3



BV_{DSS}	-200V
$I_D @ V_{GS} = -10V, T_C = 25^\circ C$	-3.9A
$I_D @ V_{GS} = -10V, T_A = 25^\circ C$	-1A
$R_{DS(ON) typ. @ V_{GS} = -10V, I_D = -1A$	0.75Ω

KSPREJ0P20



G : Gate S : Source D : Drain

Ordering Information

Device	Package	Shipping
KSPREJ0P20	DFN3×3 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel

Absolute Maximum Ratings (T_A=25°C)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	V _{DS}	-200	V
Gate-Source Voltage	V _{GS}	±20	
Continuous Drain Current @ V _{GS} =-10V, T _C =25°C	I _D	-3.9	A
Continuous Drain Current @ V _{GS} =-10V, T _C =100°C		-2.5	
Continuous Drain Current @ V _{GS} =-10V, T _A =25°C		-1	
Continuous Drain Current @ V _{GS} =-10V, T _A =70°C		-0.8	
Pulsed Drain Current	I _{DM}	-9.7	
Continuous Body Diode Forward Current @ T _C =25°C	I _S	-3.9	
Avalanche Current @ L=0.1mH	I _{AS}	-9	
Avalanche Energy @ L=0.5mH	E _{AS}	15	mJ
Total Power Dissipation	T _C =25°C	33	W
	T _C =100°C	13	
	T _A =25°C	2.3	
	T _A =70°C	1.5	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55~+150	°C

Thermal Data

Parameter	Symbol	Steady State	Unit
Thermal Resistance, Junction-to-case	R _{θJC}	3.8	°C/W
Thermal Resistance, Junction-to-ambient	R _{θJA}	53	

Note:

- *a. The power dissipation P_D is based on T_{J(MAX)}=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
- *b. The value of R_{θJA} is measured with the device mounted on 1 in² FR -4 board with 2 oz. copper, in a still air environment with T_A=25°C. The power dissipation P_D is based on R_{θJA} and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
- *c. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C. Ratings are based on low frequency and low duty cycles to keep initial T_J=25°C.

Electrical Characteristics (T_A=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS}	-200	-	-	V	V _{GS} =0V, I _D =-250μA
V _{GS(th)}	-2	-	-4		V _{DS} =V _{GS} , I _D =-250μA
G _{FS}	-	3	-	S	V _{DS} =-10V, I _D =-1A
I _{GSS}	-	-	±100	nA	V _{GS} =±20V, V _{DS} =0V
I _{DSS}	-	-	-1	μA	V _{DS} =-160V, V _{GS} =0V
R _{DS(ON)}	-	0.75	1	Ω	V _{GS} =-10V, I _D =-1A
Dynamic					
C _{iss}	-	680	-	pF	V _{DS} =-100V, V _{GS} =0V, f=1MHz
C _{oss}	-	30	-		
C _{rss}	-	25	-		
R _g	-	11	-	Ω	f=1MHz
Q _g *1, 2	-	15	-	nC	V _{DS} =-100V, I _D =-1A, V _{GS} =-10V
Q _{gs} *1, 2	-	3.4	-		
Q _{gd} *1, 2	-	3.8	-		
t _{d(ON)} *1, 2	-	11	-	ns	V _{DS} =-100V, I _D =-1A, V _{GS} =-10V, R _{GS} =1Ω
t _r *1, 2	-	18	-		
t _{d(OFF)} *1, 2	-	37	-		
t _f *1, 2	-	80	-		
Source-Drain Diode					
V _{SD} *1	-	-0.79	-1.2	V	I _S =-1A, V _{GS} =0V
t _{rr}	-	43	-	ns	I _F =-1A, dI _F /dt=100A/μs
Q _{rr}	-	73	-	nC	

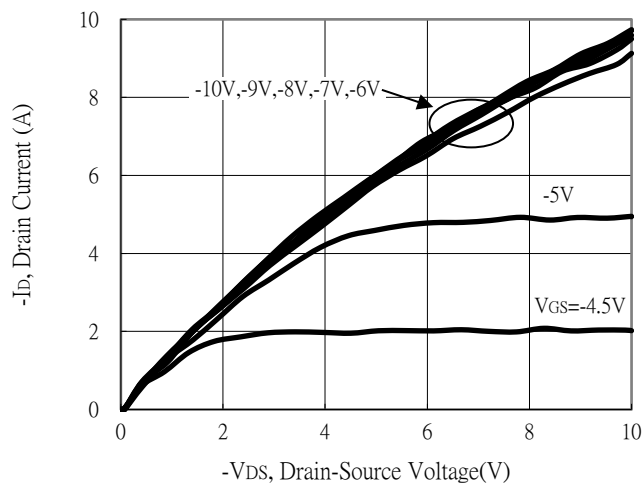
Note:

*1. Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

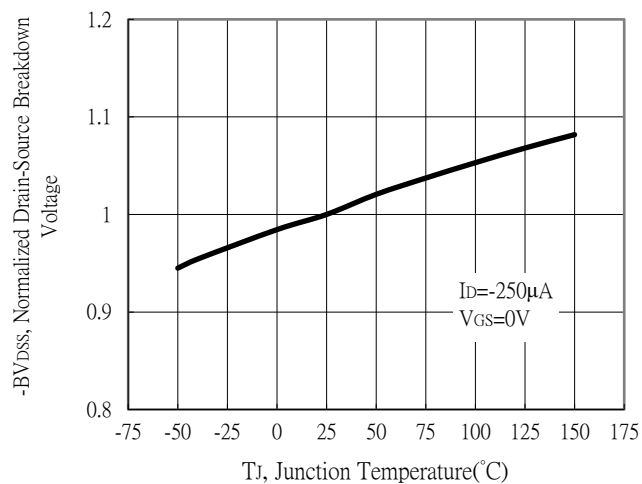
*2. Independent of operating temperature

Typical Characteristics

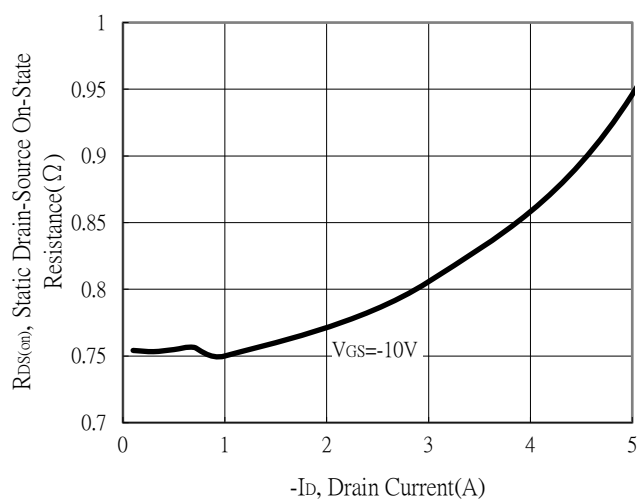
Typical Output Characteristics



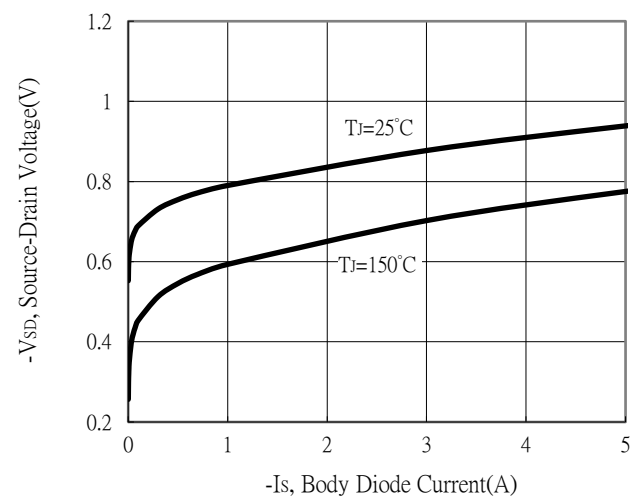
Breakdown Voltage vs Ambient Temperature



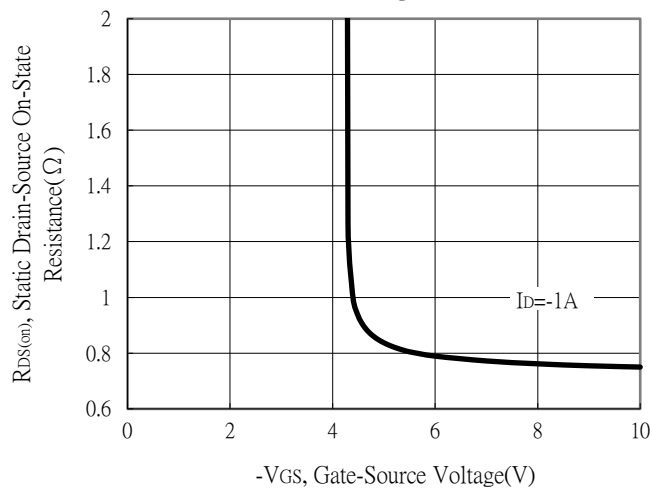
Static Drain-Source On-State resistance vs Drain Current



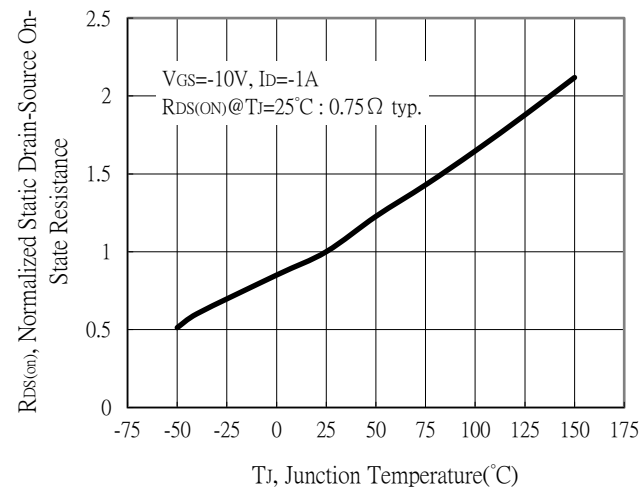
Body Diode Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

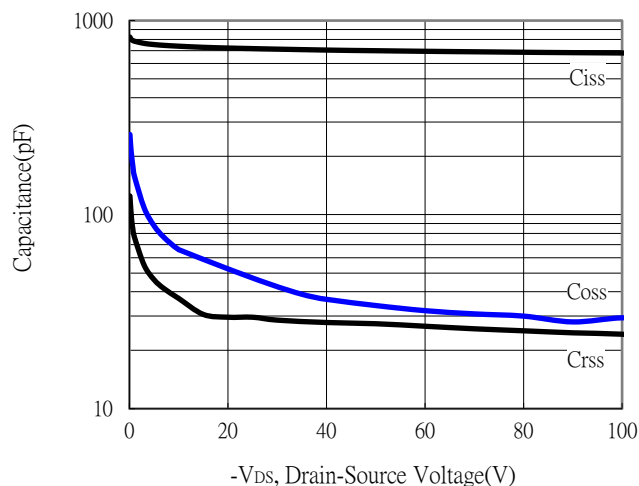


Drain-Source On-State Resistance vs Junction Temperature

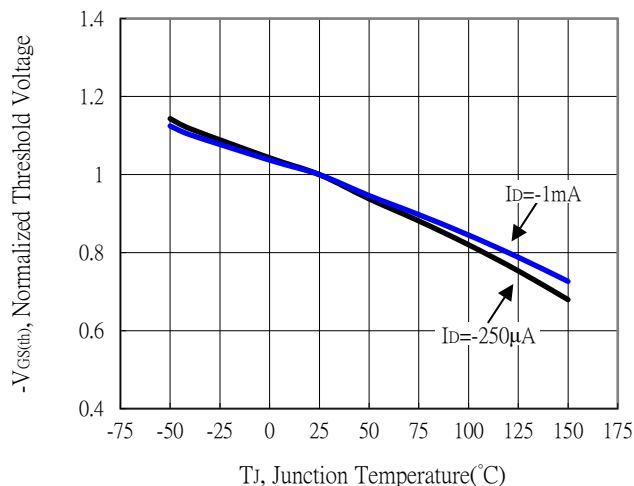


Typical Characteristics (Cont.)

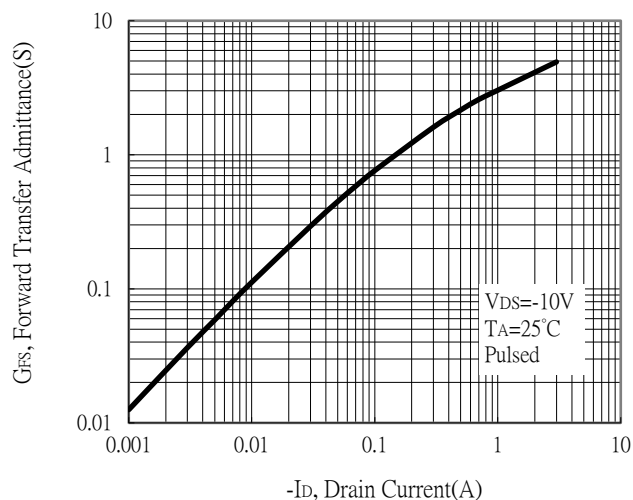
Capacitance vs Drain-to-Source Voltage



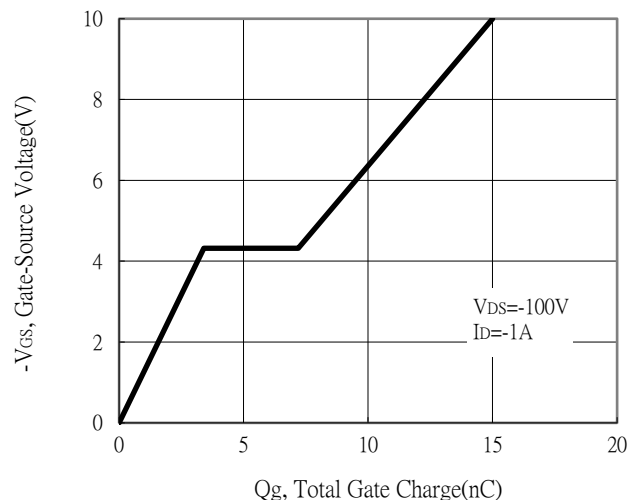
Threshold Voltage vs Junction Temperature



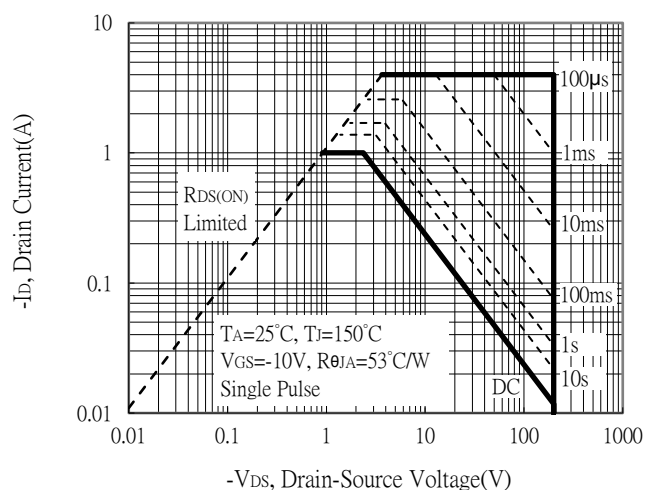
Forward Transfer Admittance vs Drain Current



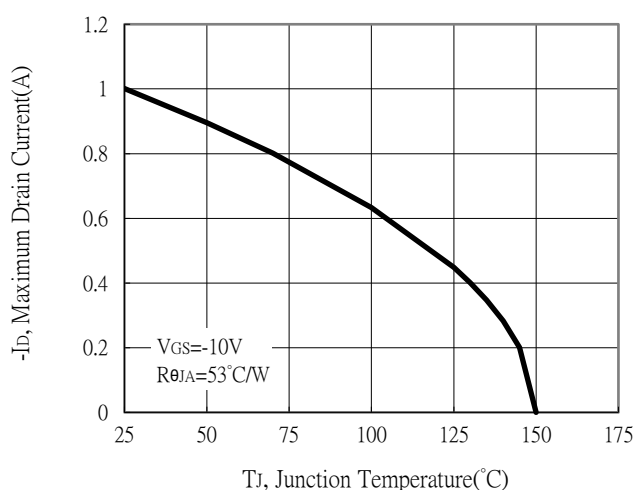
Gate Charge Characteristics



Maximum Safe Operating Area

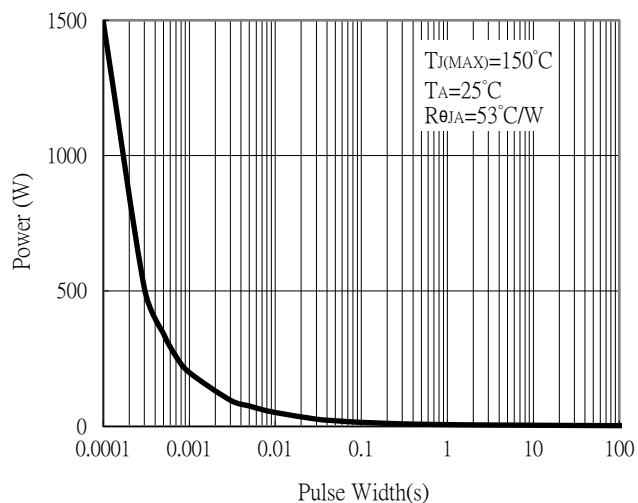


Maximum Drain Current vs Junction Temperature

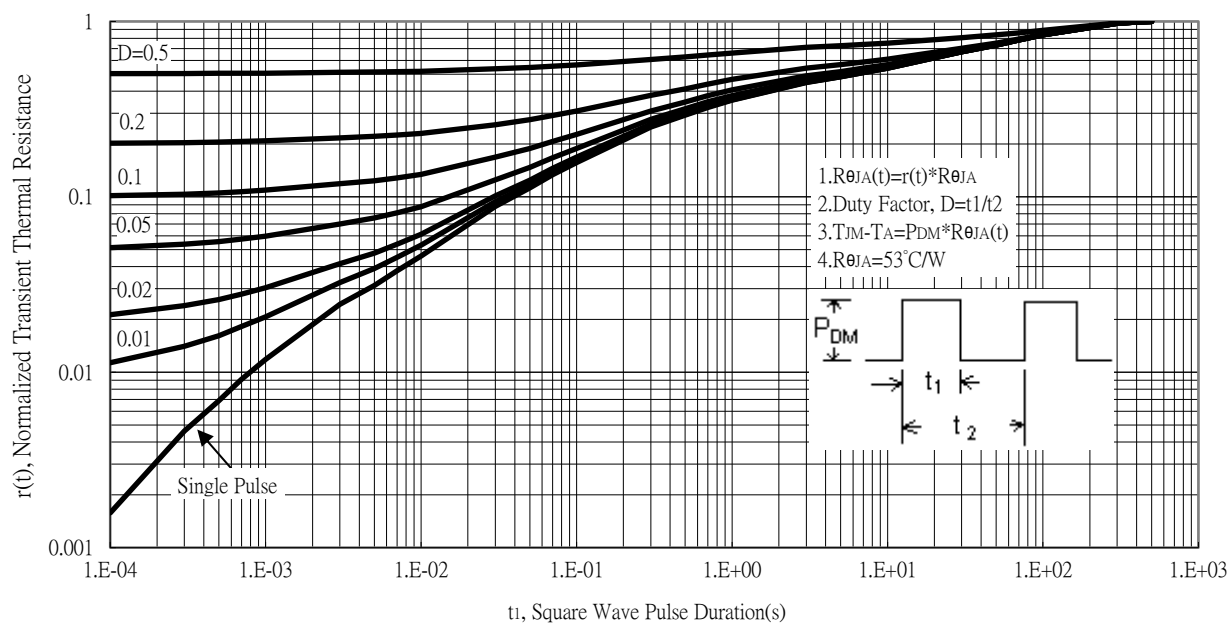


Typical Characteristics (Cont.)

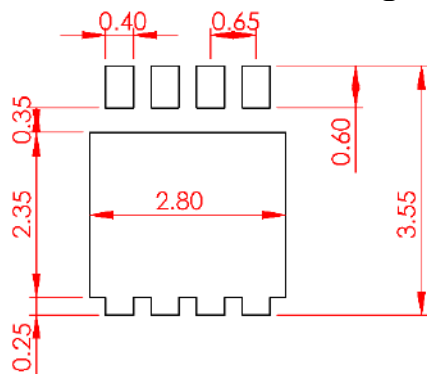
Single Pulse Power Rating, Junction to Ambient



Transient Thermal Response Curves

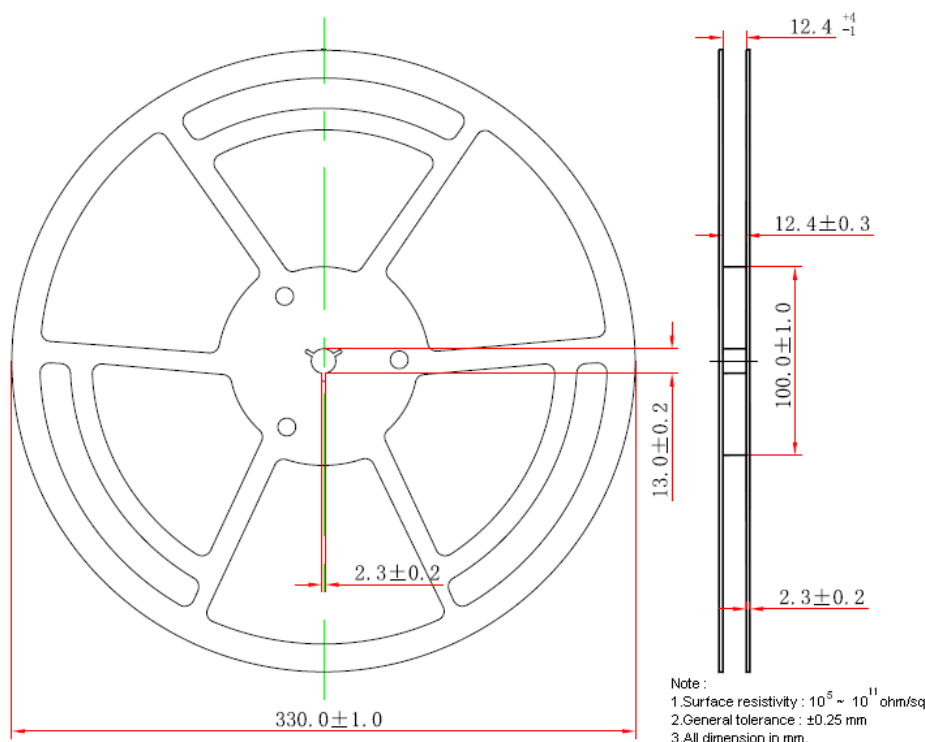


Recommended Soldering Footprint

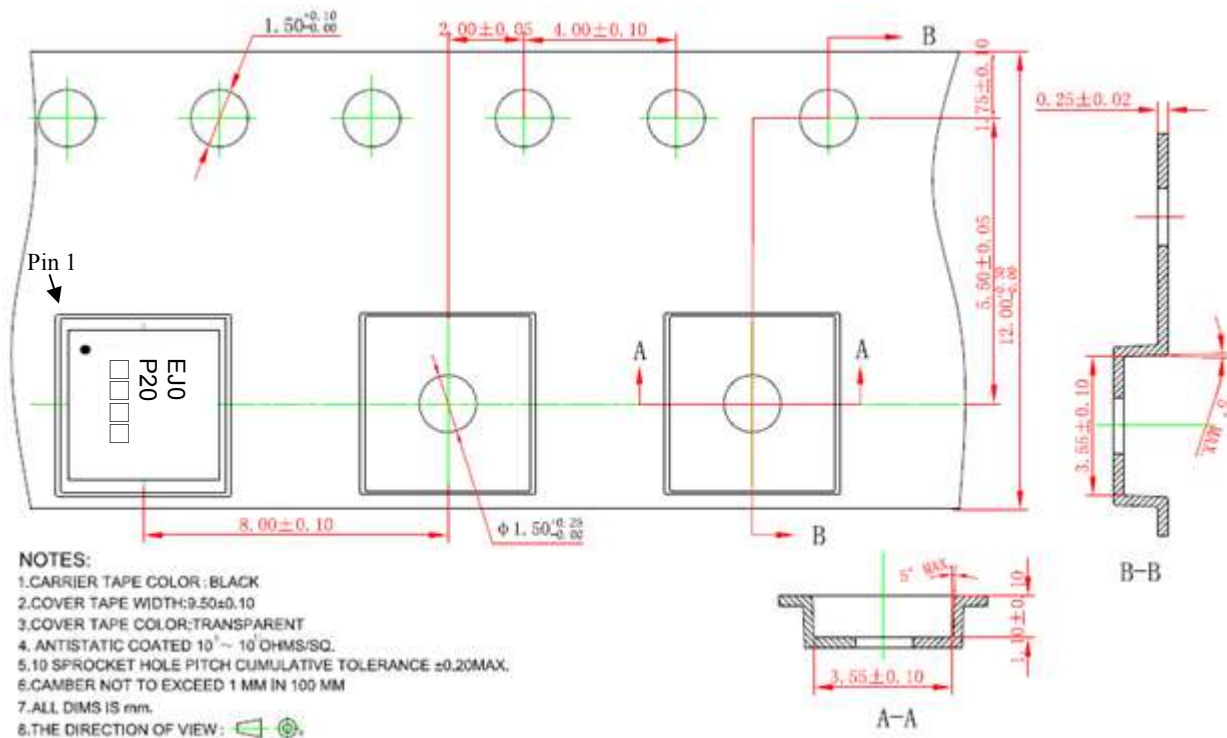


Unit : mm

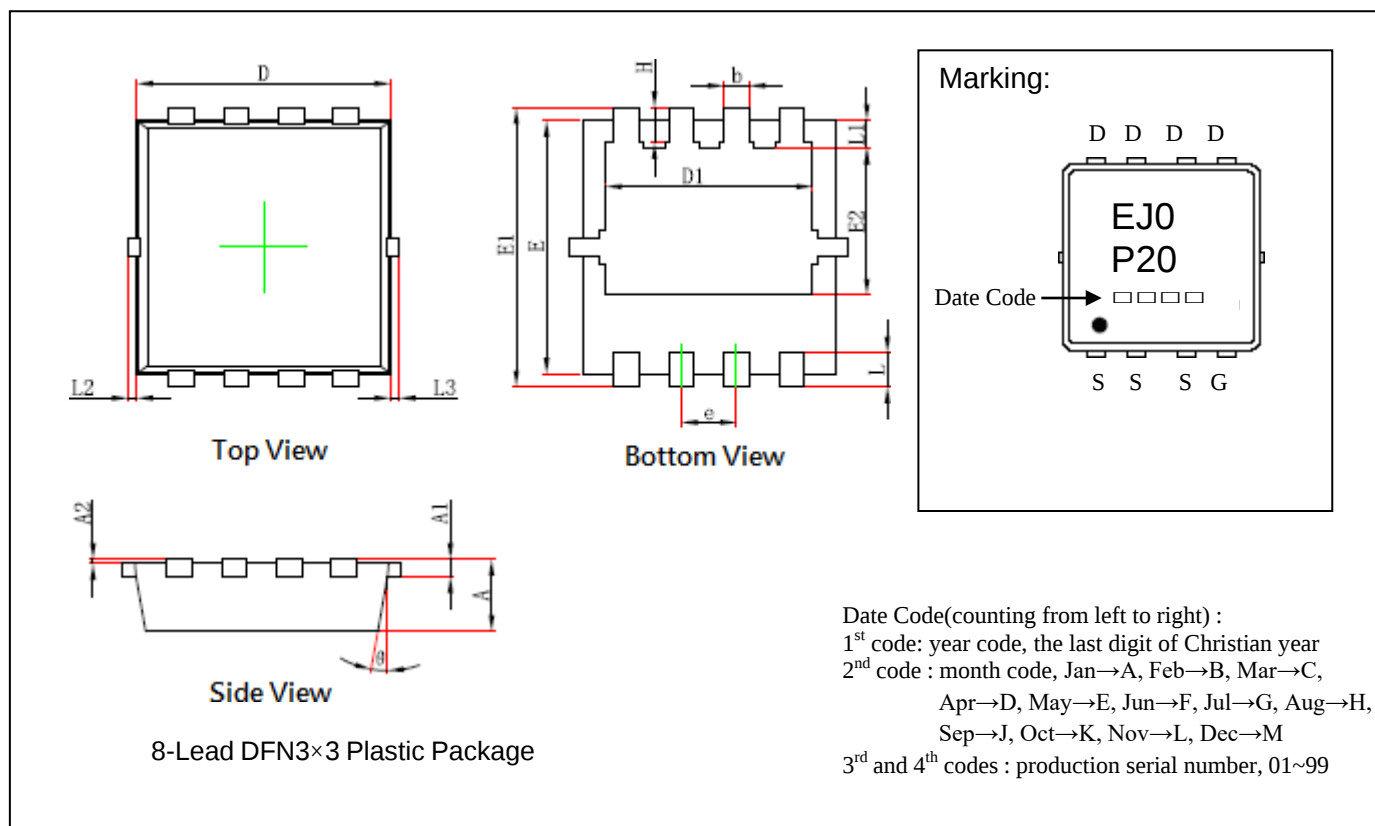
Reel Dimension



Carrier Tape Dimension



DFN3×3 Dimension



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.026	0.033	0.650	0.850	b	0.008	0.016	0.200	0.400
A1	0.006	REF	0.152	REF	e	0.022	0.030	0.550	0.750
A2	0.000	0.002	0.000	0.050	L	0.012	0.020	0.300	0.500
D	0.114	0.122	2.900	3.100	L1	0.007	0.019	0.180	0.480
D1	0.091	0.102	2.300	2.600	L2	0.000	0.004	0.000	0.100
E	0.114	0.122	2.900	3.100	L3	0.000	0.004	0.000	0.100
E1	0.124	0.136	3.150	3.450	H	0.012	0.020	0.315	0.515
E2	0.060	0.076	1.535	1.935	θ	9°	13°	9°	13°